CLAIMS

1. A polishing composition for polishing copper or a copper alloy and a resin, the polishing composition comprising:

alumina abrasive grains;

glycine;

a hydrogen peroxide solution; and

water, wherein

the content of the alumina abrasive grains is 3.0 mass % or less,

the polishing composition further comprises an anionic surfactant, and

the content of the anionic surfactant is 0.5 mass % or more.

2. The polishing composition according to claim 1, wherein the anionic surfactant is an alkylbenzenesulfonic acid.

3. The polishing composition according to claim 1 or 2, having a pH of 7.0 or more and 11.0 or less.

4. A method for adjusting a polishing speed using the polishing composition according to any one of claims 1 to 3, the method comprising:

adjusting to increase or decrease a polishing speed for copper or a copper alloy relative to a polishing speed for a resin by accordingly adjusting to increase or decrease the content of the glycine.